

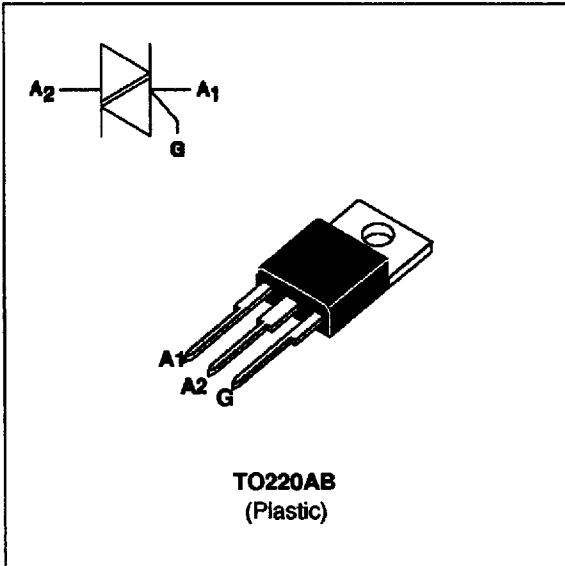
## SNUBBERLESS TRIACS

### FEATURES

- HIGH COMMUTATION :  $(dI/dt)_c > 7A/\mu s$  without snubber
- HIGH SURGE CURRENT :  $I_{TSM} = 80A$
- $V_{DRM}$  UP TO 800V
- BTA Family :
  - INSULATING VOLTAGE = 2500V(RMS)
  - (UL RECOGNIZED : E81734)

### DESCRIPTION

The BTA/BTB08 BW/CW triac family are high performance glass passivated chips technology. The SNUBBERLESS™ concept offer suppression of RC network and it is suitable for application such as phase control and static switching on inductive or resistive load.



### ABSOLUTE RATINGS (limiting values)

Symbol	Parameter			Value	Unit
$I_T(\text{RMS})$	RMS on-state current (360° conduction angle)	BTA	$T_c = 90^\circ\text{C}$	8	A
		BTB	$T_c = 95^\circ\text{C}$		
$I_{TSM}$	Non repetitive surge peak on-state current ( $T_j$ initial = 25°C )		$t_p = 8.3 \text{ ms}$	85	A
			$t_p = 10 \text{ ms}$	80	
$I_{2t}$	$I_{2t}$ value		$t_p = 10 \text{ ms}$	32	$\text{A}^2\text{s}$
$dI/dt$	Critical rate of rise of on-state current Gate supply : $I_G = 500\text{mA}$ $di_G/dt = 1\text{A}/\mu\text{s}$		Repetitive $F = 50 \text{ Hz}$	20	$\text{A}/\mu\text{s}$
			Non Repetitive	100	
$T_{stg}$ $T_j$	Storage and operating junction temperature range			- 40 to + 150 - 40 to + 125	$^\circ\text{C}$ $^\circ\text{C}$
	Maximum lead temperature for soldering during 10 s at 4.5 mm from case			260	$^\circ\text{C}$

Symbol	Parameter	BTA / BTB08... BW/CW				Unit
		400	600	700	800	
$V_{DRM}$ $V_{RRM}$	Repetitive peak off-state voltage $T_j = 125^\circ\text{C}$	400	600	700	800	V

**THERMAL RESISTANCES**

Symbol	Parameter	Value		Unit
R <sub>th</sub> (j-a)	Junction to ambient	60		°C/W
R <sub>th</sub> (j-c) DC	Junction to case for DC	BTA	4.4	°C/W
		BTB	3.3	
R <sub>th</sub> (j-c) AC	Junction to case for 360° conduction angle (F= 50 Hz)	BTA	3.3	°C/W
		BTB	2.5	

**GATE CHARACTERISTICS (maximum values)**

P<sub>G</sub> (AV) = 1W    P<sub>GM</sub> = 10W (tp = 20 μs)    I<sub>GM</sub> = 4A (tp = 20 μs)    V<sub>GM</sub> = 16V (tp = 20 μs).

**ELECTRICAL CHARACTERISTICS**

Symbol	Test Conditions	Quadrant		Suffix		Unit	
				BW	CW		
I <sub>GT</sub>	V <sub>D</sub> =12V (DC) R <sub>L</sub> =33Ω	T <sub>j</sub> =25°C	I-II-III	MIN	2	1	mA
				MAX	50	35	
V <sub>GT</sub>	V <sub>D</sub> =12V (DC) R <sub>L</sub> =33Ω	T <sub>j</sub> =25°C	I-II-III	MAX	1.5		V
V <sub>GD</sub>	V <sub>D</sub> =V <sub>DRM</sub> R <sub>L</sub> =3.3kΩ	T <sub>j</sub> =125°C	I-II-III	MIN	0.2		V
t <sub>gt</sub>	V <sub>D</sub> =V <sub>DRM</sub> I <sub>G</sub> = 500mA dI <sub>G</sub> /dt = 3A/μs	T <sub>j</sub> =25°C	I-II-III	TYP	2		μs
I <sub>L</sub>	I <sub>G</sub> =1.2 I <sub>GT</sub>	T <sub>j</sub> =25°C	I-III	TYP	40	-	mA
			II	TYP	80	-	
			I-III	MAX	-	50	
			II	MAX	-	80	
I <sub>H</sub> *	I <sub>T</sub> = 500mA gate open	T <sub>j</sub> =25°C		MAX	50	35	mA
V <sub>TM</sub> *	I <sub>TM</sub> = 11A tp= 380μs	T <sub>j</sub> =25°C		MAX	1.75		V
I <sub>DRM</sub> I <sub>RRM</sub>	V <sub>DRM</sub> Rated V <sub>RRM</sub> Rated	T <sub>j</sub> =25°C		MAX	0.01		mA
		T <sub>j</sub> =125°C		MAX	2		
dV/dt *	Linear slope up to V <sub>D</sub> =67%V <sub>DRM</sub> gate open	T <sub>j</sub> =125°C		MIN	500	250	V/μs
				TYP	750	500	
(dl/dt)c *	Without snubber	T <sub>j</sub> =125°C		MIN	7	4.5	A/ms
				TYP	14	9	

\* For either polarity of electrode A2 voltage with reference to electrode A1.

## ORDERING INFORMATION

Package	$I_T(\text{RMS})$	V <sub>DRM</sub> / V <sub>RRM</sub>	Sensitivity Specification	
			BW	CW
BTA (Insulated)	8	400	X	X
		600	X	X
		700	X	X
		800	X	X
BTB (Uninsulated)	8	400	X	X
		600	X	X
		700	X	X
		800	X	X

Fig.1 : Maximum RMS power dissipation versus RMS on-state current (F=50Hz).  
(Curves are cut off by (dI/dt)<sub>c</sub> limitation)

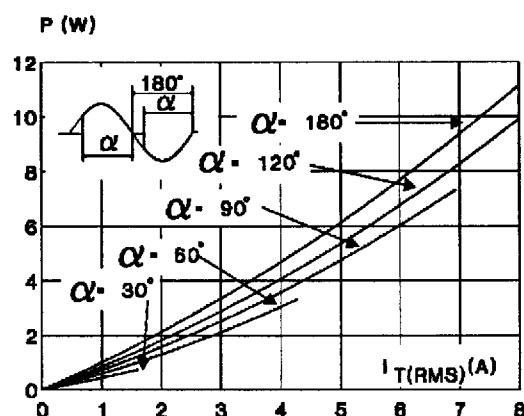


Fig.2 : Correlation between maximum RMS power dissipation and maximum allowable temperatures ( $T_{\text{amb}}$  and  $T_{\text{case}}$ ) for different thermal resistances heatsink + contact (BTA).

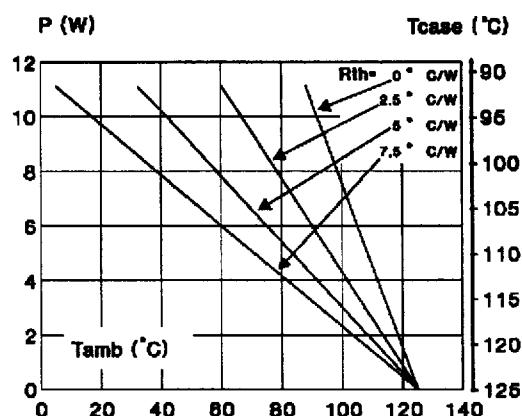


Fig.3 : Correlation between maximum RMS power dissipation and maximum allowable temperatures ( $T_{\text{amb}}$  and  $T_{\text{case}}$ ) for different thermal resistances heatsink + contact (BTB).

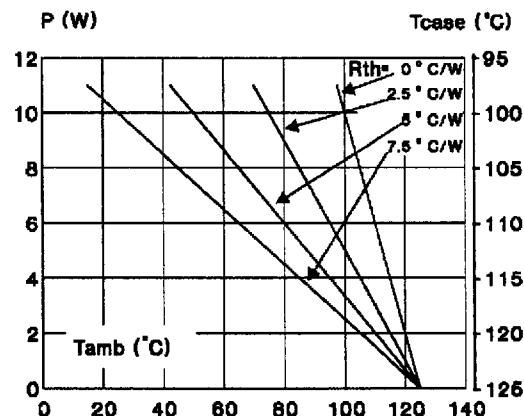
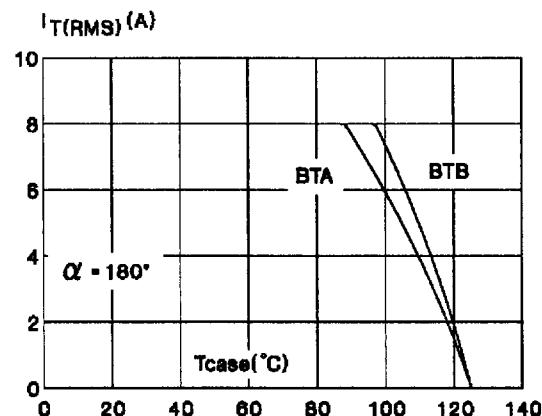


Fig.4 : RMS on-state current versus case temperature.



## BTA08 BW/CW / BTB08 BW/CW

Fig.5 : Relative variation of thermal impedance versus pulse duration.

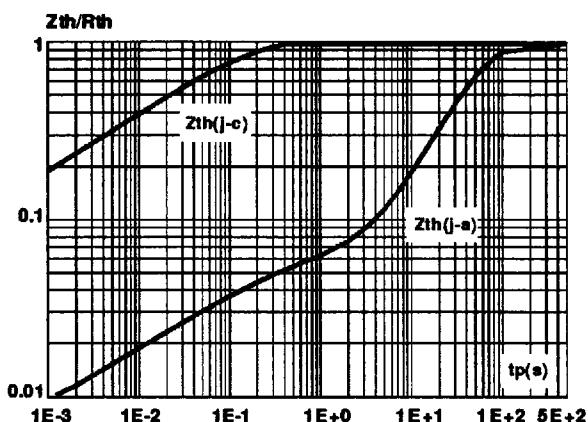


Fig.6 : Relative variation of gate trigger current and holding current versus junction temperature.

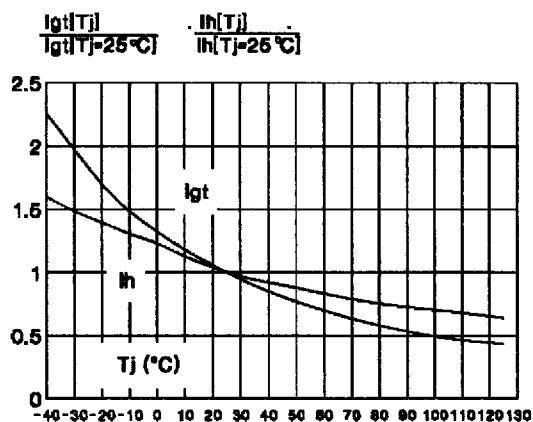


Fig.7 : Non Repetitive surge peak on-state current versus number of cycles.

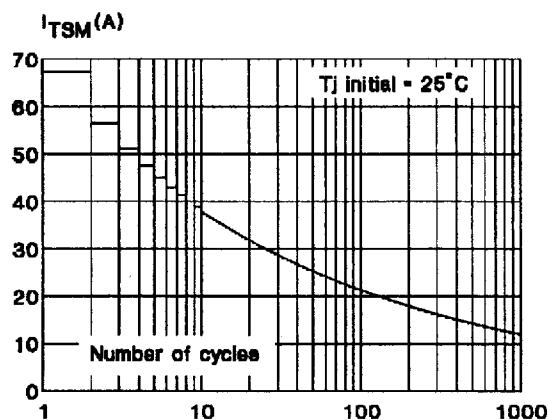


Fig.8 : Non repetitive surge peak on-state current for a sinusoidal pulse with width :  $t \leq 10\text{ms}$ , and corresponding value of  $I^2t$ .

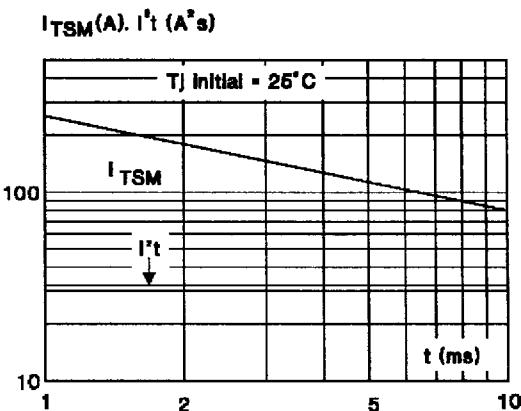
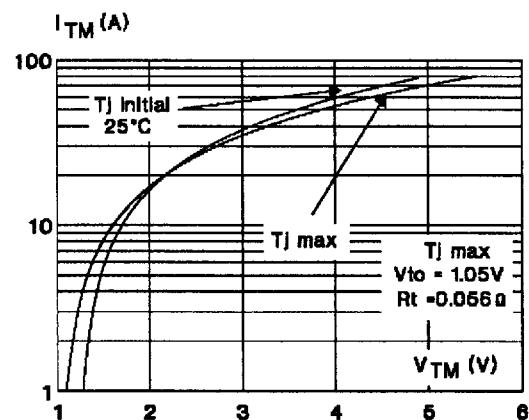
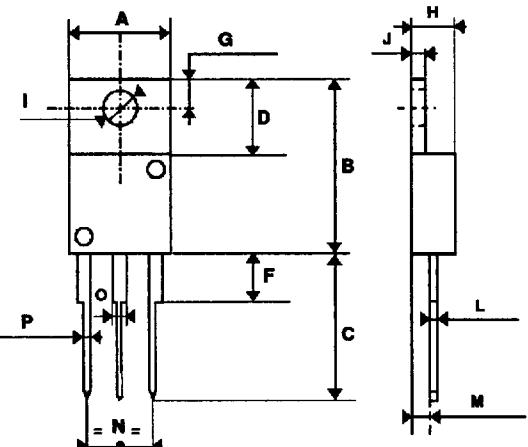


Fig.9 : On-state characteristics (maximum values).



## PACKAGE MECHANICAL DATA

TO220AB Plastic



REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	10.20	10.50	0.401	0.413
B	14.23	15.87	0.560	0.625
C	12.70	14.70	0.500	0.579
D	5.85	6.85	0.230	0.270
F		4.50		0.178
G	2.54	3.00	0.100	0.119
H	4.48	4.82	0.176	0.190
I	3.55	4.00	0.140	0.158
J	1.15	1.39	0.045	0.055
L	0.35	0.65	0.013	0.026
M	2.10	2.70	0.082	0.107
N	4.58	5.58	0.18	0.22
O	0.80	1.20	0.031	0.048
P	0.64	0.96	0.025	0.038

Cooling method : C

Marking : type number

Weight : 2.3 g

Recommended torque value : 0.8 m.N.

Maximum torque value : 1 m.N.

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